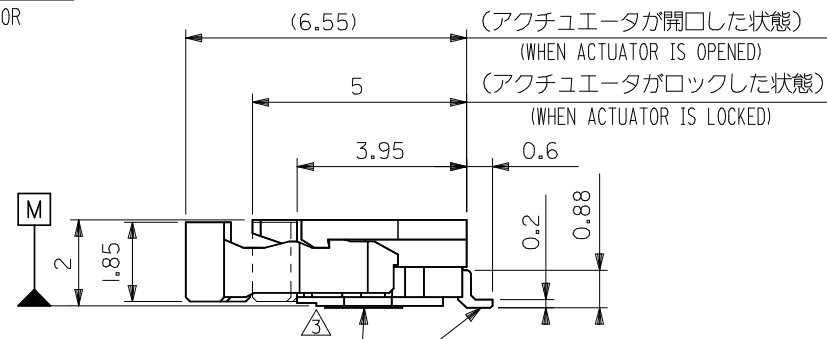
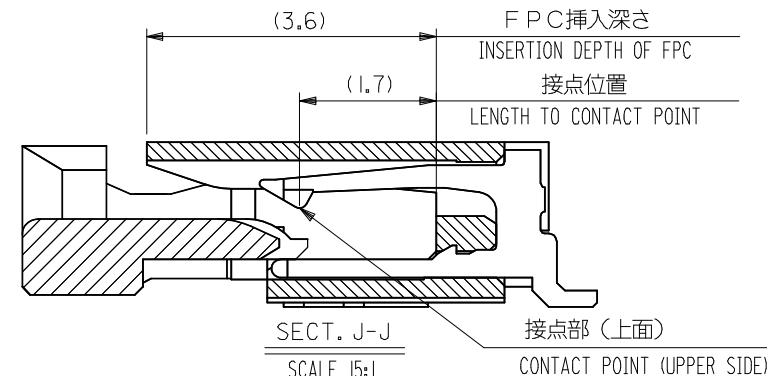
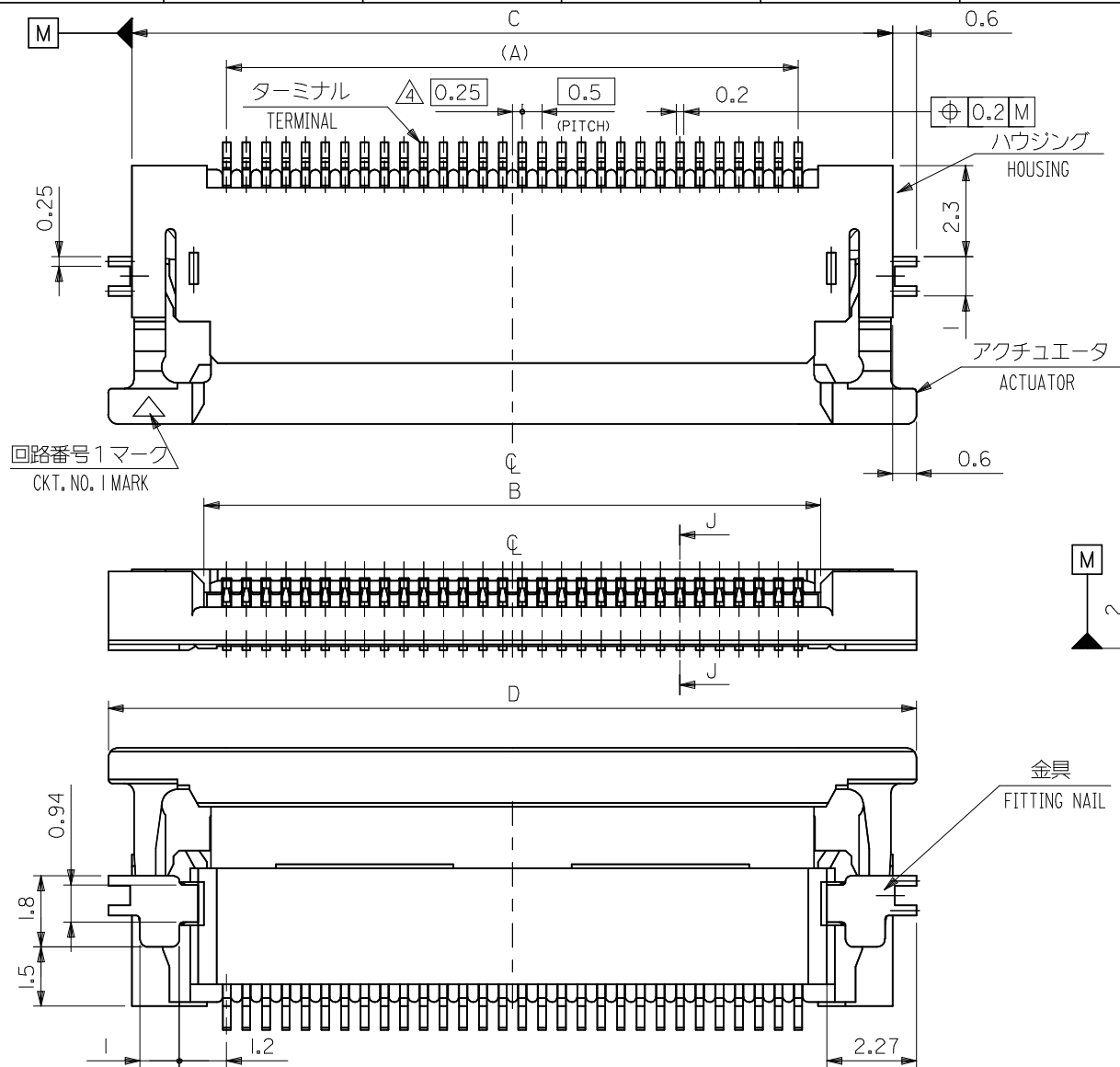
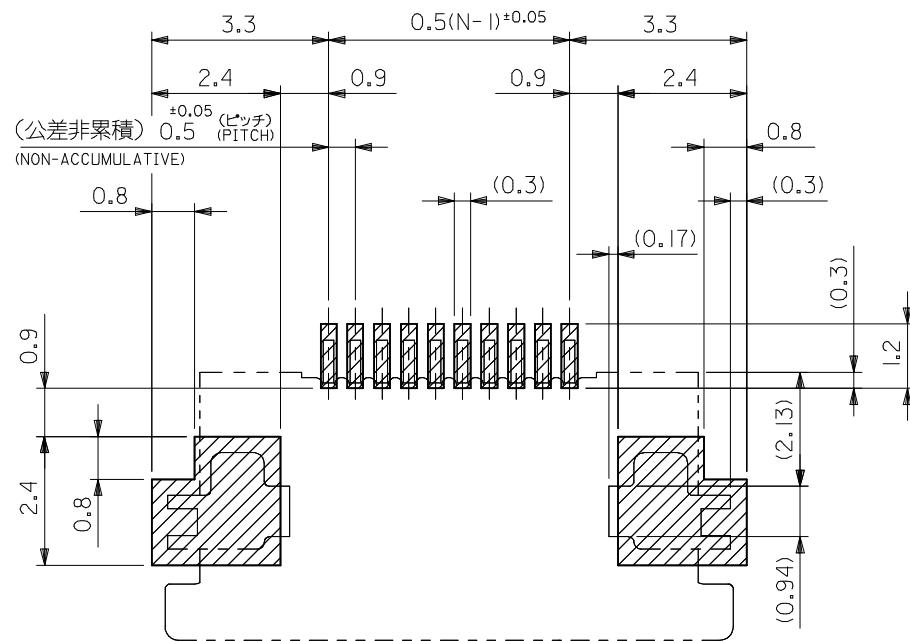




30.5	29.3	25.65	24.5	54104-5096	54104 - 5039	50
28.5	27.3	23.65	22.5	54104-4696	54104 - 4639	46
28.0	26.8	23.15	22.0	54104-4596	54104 - 4539	45
27.0	25.8	22.15	21.0	54104-4396	54104 - 4339	43
25.5	24.3	20.65	19.5	54104-4096	54104 - 4039	40
24.5	23.3	19.65	18.5	54104-3896	54104 - 3839	38
23.5	22.3	18.65	17.5	54104-3696	54104 - 3639	36
23.0	21.8	18.15	17.0	54104-3596	54104 - 3539	35
22.5	21.3	17.65	16.5	54104-3496	54104 - 3439	34
22.0	20.8	17.15	16.0	54104-3396	54104 - 3339	33
21.5	20.3	16.65	15.5	54104-3296	54104 - 3239	32
20.5	19.3	15.65	14.5	54104-3096	54104 - 3039	30
D	C	B	A	EMBOSSED TAPE	MATERIAL NO.	CIRCUIT
				ORDER No. オーダー番号		

REVISED EC NO: J2008-4308 DRWN:MABEI CHKD:THARUYAMA APPR:NUKITA	DESCRIPTION REV	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE		SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION	
				MM ONLY		---	METRIC		
		10 UNDER	± 0.2	DRAWN BY Y. SAKIYAMA	DATE '04/01/22	TITLE 0.5 FPC CONN ZIF HSG ASSY FOR SMT RA UPR CONT -LEAD FREE-			
		10 OVER 30 UNDER	± 0.25	CHECKED BY M. SASAO	DATE '04/01/22				
		30 OVER	± 0.3	APPROVED BY M. SASAO	DATE '04/01/22	molex MOLEX INCORPORATED			
		ANGULAR ±3 °	MATERIAL NO.		DOCUMENT NO.				
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3	SEE TABLE THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				



コネクタ位置
CONNECTOR POSITION

参考基板レイアウト
RECOMMENDED P.C.BOARD
PATTERN DIMENSION (REF.)

(マウント面)
(MOUNTING SIDE)

注記 NOTES

I. 使用材料 MATERIAL

ハウジング : 46ナイロン、UL94V-0
HOUSING 46NYLON

アクチュエータ : PPS、UL94V-0
ACTUATOR

ターミナル :リン青銅、ニッケル下地 錫ピスマスメッキ (t=0.2)
 TERMINAL PHOS-BRONZE, TIN-BISMUTH

金具 : リン青銅、ニッケル下地 錫メッキ (t=0.2)
FITTING NAIL PHOS-BRONZE, TIN OVER NICKEL PLATING. (t=0.2)

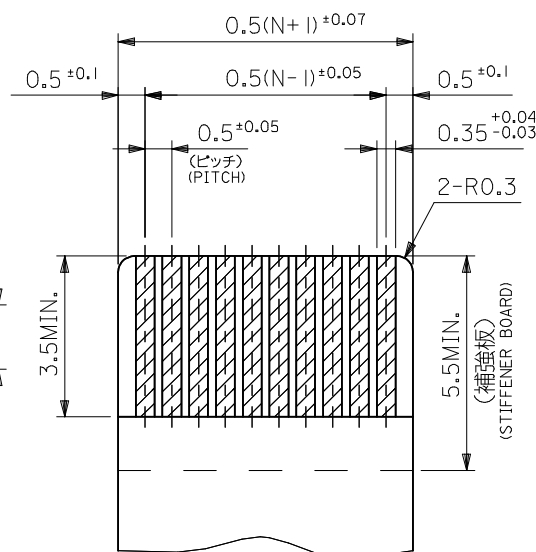
2. エンボステーパ梱包時は、アクチュエータがロックした状態とする。
IN THE PACKAGE,ACTUATOR OF PART NO.54104-***39 SHOULD BE LOCKED.

△ ソルダーテール半田付け面のズレ量、及び金具半田付け面のズレ量は、基準面 H に対し上方向 0.1 MAX.、下方向 0.15 MAX. とし、相互のバラツキ量は、0.1 MAX. とする。
MISALIGNMENT OF SOLDER TAILS AND FITTING NAILS FROM UPPER DIRECTION: 0.1 MAX. , LOWER DIRECTION: 0.15 MAX. OFFSET BETWEEN UPPER AND LOWER 0.1 MAX. H

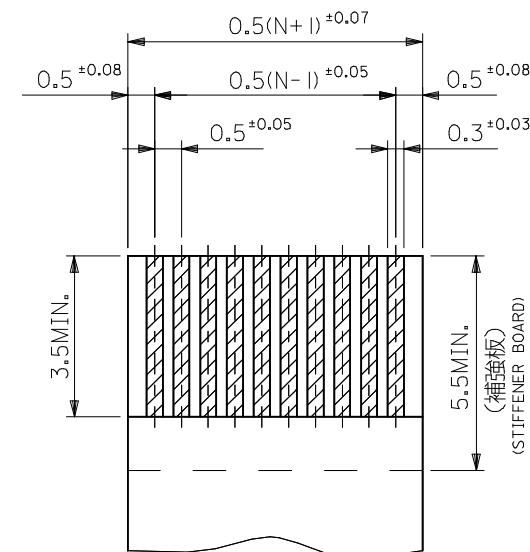
△4 偶数極に適用。
APPLY FOR EVEN CIRCUIT.

△ パターンはくり止め用金具
FITTING NAIL FOR PREVENTION OF PEELING OF P.C.B. PATTERN.

6. 本製品は 54104-**37 の鉛フリー品である。
THIS PRODUCT IS LEAD FREE OF 54104-**37.



適合FPC推奨寸法
APPLICABLE FPC
RECOMMENDED DIMENSION
(仕上がり厚さ: $0.3^{+0.03}$)
(THICKNESS: $0.3^{+0.03}$)



適合FFC推奨寸法
APPLICABLE FFC
RECOMMENDED DIMENSION

(仕上がり厚さ: 0.3 ± 0.03)
(THICKNESS: 0.3 ± 0.03)

FPC/FFCについて

打抜き方向は導体側から補強板側を推奨いたします。
導体部については軟銅箔35マイクロメートルまたは50マイクロメートル
メッキ厚 3~9マイクロメートル錫または半田メッキ（電気メッキ）

RECOMMENDED PUNCHER DIRECTION:
FROM CONDUCTOR SIDE TO STIFFENER BOARD SIDE.
RECOMMENDED CONDUCTOR SPEC.:
THICKNESS OF SOFT COPPER FOIL:
35 micrometer or 50 micrometer
TIN OR SOLDER PLATING:
3 ~ 9 micrometer(ELECTRICAL PLATING)

FPCについて

補強フィルム材質はポリリットを推奨致します。
接着剤は熱硬化接着剤を推奨致します。

RECOMMENDED MATERIAL:
STIFFENER FILM : POLYIMIDE
BONDING AGENT : THERMOSETTING BONDING AGENT

FREE OF 54104-***37.		54104-***39		MODEL NO.	
GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC
				THIRD ANGLE PROJECTION	
DRAWN BY DATE Y. SAKIYAMA '04/01/22		TITLE 0.5 FPC CONN ZIF HSG ASSY FOR SMT RA UPR CONT -LEAD FREE-			
CHECKED BY DATE M. SASAO '04/01/22					
APPROVED BY DATE M. SASAO '04/01/22		MOLEX INCORPORATED			
MATERIAL NO.					
ANGULAR ±3 °		DOCUMENT NO.		SHEET NO.	
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE SHEET 1		SD-54104-071	
		2 OF 2			
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					

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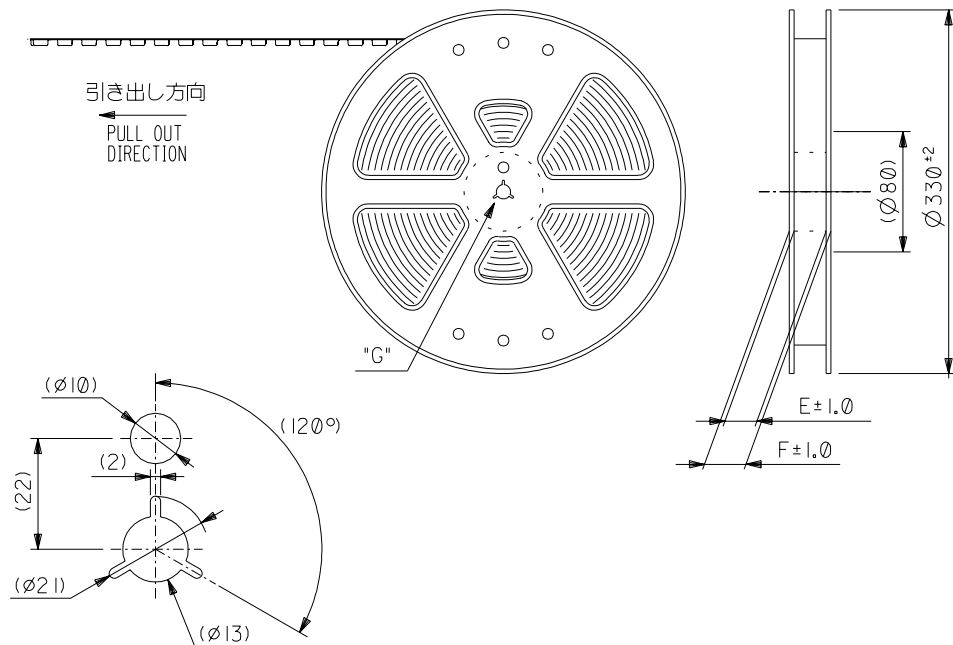
E

D

C

B

A



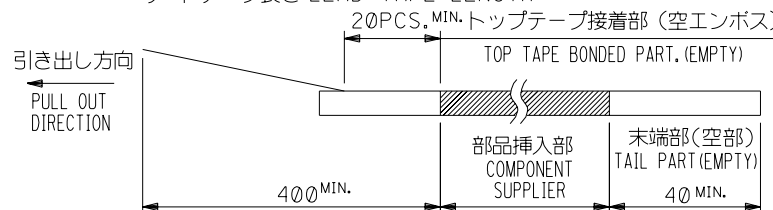
DETAIL "G"

4. 材料(MATERIAL)
キャリアテープ(CARRIER TAPE): ポリプロピレン(POLYPROPYLENE)
トップテープ(TOPTAPE): PET, PE, PEF
リール(REEL): ポリスチレン(PS)<リサイクル材を含む>
POLYSTYRENE (PS) <RECYCLE MATERIAL CONTAINED>

5. 本製品は 54104-***92 の鉛フリー品である。
THIS PRODUCT IS LEAD FREE OF 54104-***92.

NOTES

1. 梱包数量: 1500個/リール
NUMBER OF CONNECTORS: 1500PCS/REEL
2. リードテープ長さ LEAD TAPE LENGTH



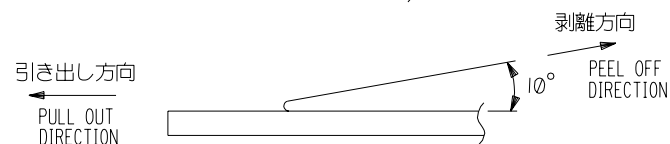
3. トップテープの剥離強度: 0.1~1.3N (10~130gf)
(剥離方向は下図参照)

尚、本規格値は出荷時に適用。(但し、輸送時に剥離が発生しないこと。)

PEELING OFF FORCE OF TOP TAPE: 0.1~1.3N (10~130gf)

(PEELING DIRECTION AS SHOWN IN FOLLOWING FIG.)

THIS REQUIREMENT SHOULD BE APPLIED AT SHIPMENT.
PEEL OFF SHOULD NOT BE ALLOWED, DURING TRANSPORTATION.



44	49.4	45.4	30.8	31.9	26.1	29.6	54104-5096	50
			28.8	29.9	24.1	27.6	-4696	46
			28.3	29.4	23.6	27.1	-4596	45
			27.3	28.4	22.6	26.1	-4396	43
			25.8	26.9	21.1	24.6	-4096	40
			24.8	25.9	20.1	23.6	-3896	38
			23.8	24.9	19.1	22.6	-3696	36
			23.3	24.4	18.6	22.1	-3596	35
			22.8	23.9	18.1	21.6	-3496	34
			22.3	23.4	17.6	21.1	-3396	33
			21.8	22.9	17.1	20.6	-3296	32
			20.8	21.9	16.1	19.6	54104-3096	30
キャリアテープ幅 CARRIER TAPE WIDTH	F	E	D	C	B	A	MATERIAL NO.	CIRCUIT

EC NO. DRWN: CHK: APPR:	EC NO. DRWN: CHK: APPR:	EC NO. DRWN: CHK: APPR:	REVISED '04/04/21 EC NO. J2004-3918 DRWN: Y.WADA CHK: M.SASAO APPR: M.SASAO	RELEASED '04/01/22 EC NO. J2004-2032 DRWN: Y.SAKIYAMA CHK: M.SASAO APPR: M.SASAO	DESCRIPTION 材料 注記参照 SEE NOTES	GENERAL TOLERANCES: (UNLESS SPECIFIED) 一般公差		SCALE —	DESIGN UNITS ☒ mm ☐ INCH	 THIRD ANGLE PROJECTION	☐ mm INCH ☐ INCH ☒ mm ONLY	REVISE ON CAD ONLY
						10 UNDER 未満	±0.2	DRAWN BY & DATE Y.SAKIYAMA '04/01/22			TITLE: Embstp Pkg for 0.5 FPC Conn Zif Hsg Assy -LEAD FREE-	
						10 OVER 以上30 UNDER 未満	±0.25	CHECKED BY & DATE M.SASAO '04/01/22				
						30 OVER 以上	±0.3	APPROVED BY & DATE M.SASAO '04/01/22			MOLEX MOLEX INCORPORATED	
WIRE RANGE 適用電線範囲						—	ANGLE 角度	3°	CAD FILENAME SD-54104-072.S01	MATERIAL NO. SEE CHART	DRAWING NO. SD-54104-072	SHEET NO. 1 OF 2
INS. RANGE 被覆外径						—	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION.					SIZE B

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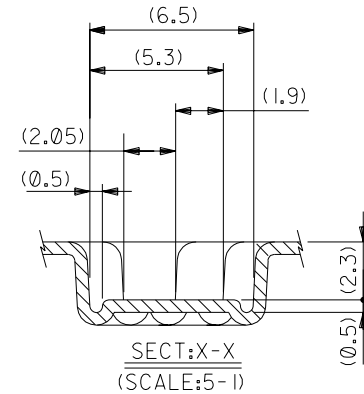
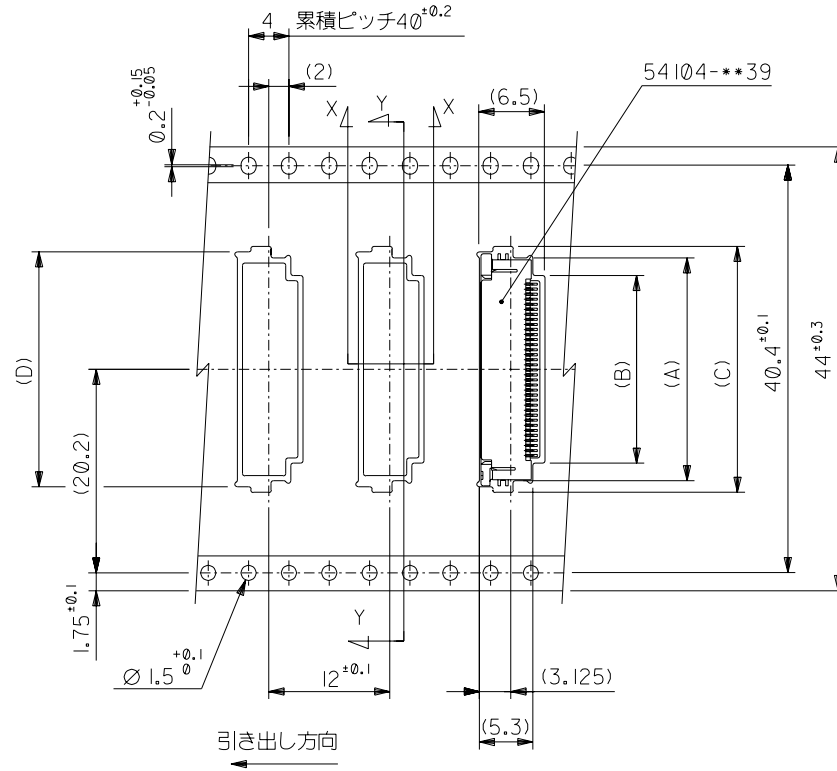
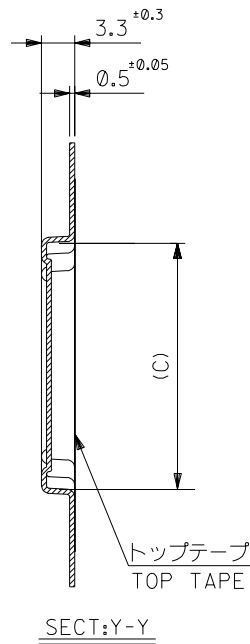
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EN-02J(097) MXJ-54



EC NO.
DRWN:
CHK:
APPR:

EC NO.
DRWN:
CHK:
APPR:

EC NO.
DRWN:
CHK:
APPR:

REVISED '04/04/21
EC NO. J2004-3918
DRWN: Y.WADA
CHK: M.SASAO
APPR: M.SASAO

RELEASED '04/01/22
EC NO. J2004-2032
DRWN: Y.SAKIYAMA
CHK: M.SASAO
APPR: M.SASAO

DESCRIPTION

MATERIAL
材料

SHEET 1 OF 2 参照
REFER TO SHEET 1 OF 2

FINISH
仕上げ

WIRE RANGE
適用電線範囲

REV

INS. RANGE
被覆外径

GENERAL TOLERANCES:
(UNLESS SPECIFIED)
一般公差

10 UNDER 未満

10 OVER 以上 30 UNDER 未満

30 OVER 以上

ANGLE 角度

SCALE

MODEL NO.
DESIGN UNITS
THIRD ANGLE
PROJECTION

DRAWN BY & DATE
Y.SAKIYAMA '04/01/22

CHECKED BY & DATE
M.SASAO '04/01/22

APPROVED BY & DATE
M.SASAO '04/01/22

CAD FILENAME

SD-54104-072.S02

54104-**-96

THIRD ANGLE
PROJECTION

TITLE: Embstp Pkg for
0.5 FPC Conn Zif Hsg Assy
-LEAD FREE-

MOLEX INCORPORATED

MATERIAL NO.

SEE CHART

DIMENSIONS:

mm INCH mm ONLY

SH T REV

REVISE ON
CAD ONLY

DRAWING NO.

SD-54104-072

SHEET NO.

2 OF 2

SIZE
B

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INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION.